

LNPT[™] THERMOCOMP[™] COMPOUND JF004E

JF-1004 EM
REGION ASIA

DESCRIPTION

LNP THERMOCOMP JF004E compound is based on Polyethersulfone (PES) resin containing 20% glass fiber. Added features of this grade include: Easy Molding.

GENERAL INFORMATION	
Features	Good Processability, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyethersulfone (PESU)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break	114	MPa	ASTM D638
Tensile Strain, break	2.9	%	ASTM D638
Tensile Modulus, 50 mm/min	7350	MPa	ASTM D638
Flexural Stress	186	MPa	ASTM D790
Flexural modulus	6690	MPa	ASTM D790
Tensile Stress, break	109	MPa	ISO 527
Tensile Strain, break	2.9	%	ISO 527
Tensile Modulus, 1 mm/min	7350	MPa	ISO 527
Flexural Stress	183	MPa	ISO 178
Flexural Modulus	7590	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	427	J/m	ASTM D4812
Izod Impact, notched, 23°C	58	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	16	J	ASTM D3763
Multiaxial Impact	4	J	ISO 6603
Izod Impact, unnotched 80*10*4 +23°C	73	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	7	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 1.82 MPa, 3.2mm, unannealed	205	°C	ASTM D648

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	205	°C	ISO 75/Af
Relative Temp Index, Elec	180	°C	UL 746B
Relative Temp Index, Mech w/impact	180	°C	UL 746B
Relative Temp Index, Mech w/o impact	180	°C	UL 746B
PHYSICAL ⁽¹⁾			
Density	1.51	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.4	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.5 – 0.7	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.6 – 0.8	%	ASTM D955
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.5 – 0.7	%	ISO 294
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.6 – 0.8	%	ISO 294
Density	1.51	g/cm ³	ISO 1183
FLAME CHARACTERISTICS ⁽³⁾			
UL Yellow Card Link	E207780-101283849	-	-
UL Recognized, 94V-0 Flame Class Rating	0.81	mm	UL 94

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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